

Apex Microtechnology Materials Substance Report

Model: AIC1532
RoHS Complaint: Yes

Print: 02/27/2024
Lead Free: Yes

Die Substances

	Total Weight (g)
1,1-Di(t-butylperoxy)cyclohexane	7.00E-07
1,4-Cyclohexanedimethanol diglycidyl ether	8.40E-05
Bisphenol F Type Epoxy Resin	8.40E-05
Dicyandiamide	7.00E-07
Epoxy resin	1.68E-04
Ethylene dimethacrylate	1.68E-04
Hardener	8.40E-05
Silicon	4.10E-03
Silver Powder	2.21E-03

Lead Frame Substances

	Total Weight (g)
Copper	2.59E-01
Iron	6.02E-03
Phosphorus	1.37E-04
Silver	8.21E-03
Tin	3.00E-03
Zinc	1.37E-04

Mold Substances

	Total Weight (g)
Carbon Black	1.93E-03
Epoxy resin A	2.31E-02
Epoxy resin B	9.65E-03
Phenol Resin	9.65E-03
Silica(Amorphous) A	3.18E-01
Silica(Amorphous) B	2.31E-02

Wire Substances

	Total Weight (g)
Gold	2.80E-03

Substances Present in this Model	Total Weight (g)
1,1-Di(t-butylperoxy)cyclohexane	7.00E-07
1,4-Cyclohexanedimethanol diglycidyl ether	8.40E-05
Bisphenol F Type Epoxy Resin	8.40E-05
Carbon Black	1.93E-03
Copper	2.59E-01
Dicyandiamide	7.00E-07
Epoxy resin	1.68E-04
Epoxy resin A	2.31E-02
Epoxy resin B	9.65E-03
Ethylene dimethacrylate	1.68E-04
Gold	2.80E-03
Hardener	8.40E-05
Iron	6.02E-03
Phenol Resin	9.65E-03
Phosphorus	1.37E-04
Silica(Amorphous) A	3.18E-01
Silica(Amorphous) B	2.31E-02
Silicon	4.10E-03
Silver	8.21E-03
Silver Powder	2.21E-03
Tin	3.00E-03
Zinc	1.37E-04
Sum of All Substances Present in This Model (g)	6.72E-01